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**Bi-CMOS IC** 

## **LED Boost Driver with PWM Dimming**

## ON Semiconductor®

www.onsemi.com

#### **Overview**

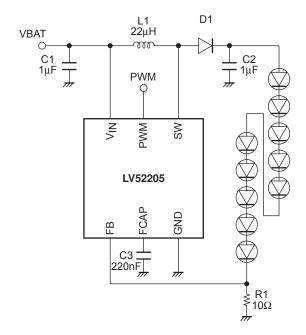
The LV52205MU is a high voltage boost driver for LED drive. LED current is set by the external resistor R1 and LED dimming can be done by changing FB voltage with PWM control.

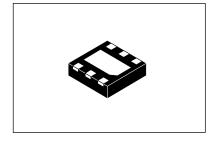
#### **Feature**

- Operating Voltage from 2.7V to 5.5V
- Integrated 42V MOSFET
- PWM dimming for Brightness Control
- 600kHz Switching Frequency

## Typical Applications

• LED Display Backlight Control





UDFN6 2×2, 0.65P

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 12 of this data sheet.

#### **Specifications**

#### Absolute Maximum Ratings at Ta = 25°C

| Parameter                   | Symbol              | Conditions      | Ratings     | Unit |
|-----------------------------|---------------------|-----------------|-------------|------|
| Maximum supply voltage      | V <sub>CC</sub> max | V <sub>CC</sub> | 5.5         | V    |
| Maximum pin voltage1        | V1 max              | SW              | 42          | V    |
| Maximum pin voltage2        | V2 max              | Other pin       | 5.5         | V    |
| Allowable power dissipation | Pd max              | Ta = 25°C *1    | 2.05        | W    |
| Operating temperature       | Topr                |                 | -30 to +85  | °C   |
| Storage temperature         | Tstg                |                 | -55 to +125 | °C   |

<sup>\*1</sup> Mounted on a specified board: 70mm×50mm×1.2mm (4 layer glass epoxy)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **Recommendation Operating Condition** at Ta = 25°C

| Parameter             | Symbol             | Conditions | Ratings     | Unit |
|-----------------------|--------------------|------------|-------------|------|
| Supply voltage range1 | V <sub>CC</sub> op | VCC        | 2.7 to 5.5  | V    |
| PWM frequency         | Fpwm               |            | 300 to 100k | Hz   |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### Electrical Characteristics Analog block at Ta = 25°C, V<sub>CC</sub> = 3.6V, unless otherwise specified

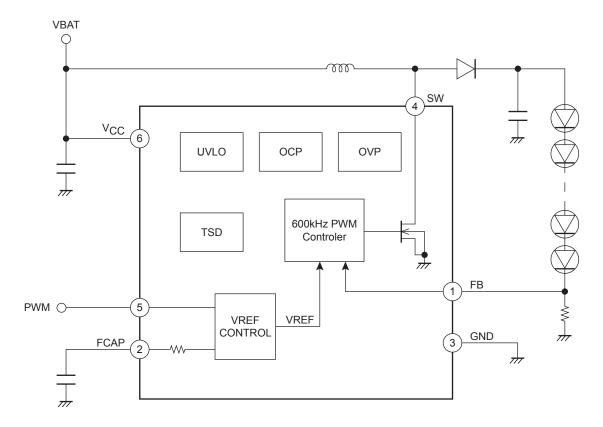
| Parameter                    | 0                 | O what  | Ratings |     |                 |      |
|------------------------------|-------------------|---|---------|-----|-----------------|------|
|                              | Symbol            | nbol Conditions                                 |         | typ | max             | Unit |
| Standby current dissipation  | I <sub>CC</sub> 1 | SHUTDOWN  |         | 0   | 5               | μΑ   |
| DC/DC current dissipation    | I <sub>CC</sub> 2 | V <sub>OUT</sub> = 30V, I <sub>LED</sub> = 20mA |         |     | 1               | mA   |
| FB voltage                   | Vfb               | PWM duty 100%                                   | 0.19    | 0.2 | 0.21            | V    |
| FB pin leak current          | Ifb               |   |         |     | 1               | μΑ   |
| OVP voltage                  | Vovp              | SW  | 40      | 41  | 42              | V    |
| SWOUT ON resistance          | Ron               | IL = 100mA                                      |         | 700 |                 | mΩ   |
| NMOS switch current limit    | ILIM              | Vfb = 200mV                                     |         | 0.7 |                 | Α    |
| OSC frequency                | Fosc              |   |         | 600 |                 | kHz  |
| High level input voltage     | V <sub>IN</sub> H | PWM   | 1.5     |     | V <sub>CC</sub> | V    |
| Low level input voltage      | V <sub>IN</sub> L | PWM   | 0       |     | 0.4             | V    |
| Under voltage lockout        | Vuvlo             | V <sub>IN</sub> falling                         |         | 2.2 |                 | V    |
| PWM setup time from shutdown | Ton               |   | 20      |     |                 | us   |
| PWM low time to shutdown     | Toff              |   | 8.9     |     |                 | ms   |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

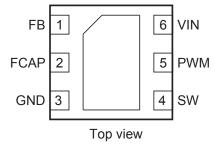
Caution 1) Absolute maximum ratings represent the values which cannot be exceeded for any length of time.

Caution 2) Even when the device is used within the range of absolute maximum ratings, as a result of continuous usage under high temperature, high current, high voltage, or drastic temperature change, the reliability of the IC may be degraded. Please contact us for the further details.

#### **Block Diagram**

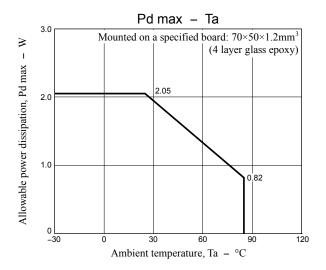


#### **Pin Connections**



#### **Pin Function**

| PIN# | Pin Name        | Description                                  |  |
|------|-----------------|--|--|
| 1    | FB              | Feedback pin.                                |  |
| 2    | FCAP            | Filtering capacitor terminal for PWM signal. |  |
| 3    | GND             | Ground                                       |  |
| 4    | SW              | Switch pin. Drain of the internal power FET. |  |
| 5    | PWM             | PWM dimming input (active High).             |  |
| 6    | V <sub>CC</sub> | Supply voltage.                              |  |
|      | Expose-pad      | Connect to GND on PCB.                       |  |



#### **LED Current Setting**

LED current is set by an external resistor connected between the FB pin and ground.

$$I_{LED} = V_{FB}/R_{FB}$$
.

The  $V_{FB}$  can be controlled by PWM signal. PWM input is converted into a near DC current by the internal resistor R that was equivalent to  $60k\Omega$  ( $\pm 10\%$ ) and the external capacitor  $C_{FCAP}$  as a low pass filter with a cut-off frequency fc =  $1/2\pi RC_{FCAP}$ . The  $V_{FB}$  can be adjusted by altering the duty cycle of the PWM signal (See Fig.1).

$$V_{FB} = 200 \text{ (mV)} \times \text{PWM Duty (\%)}$$

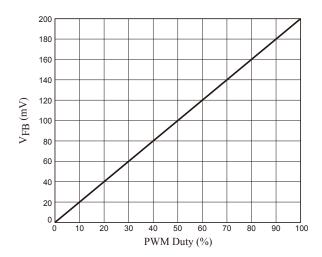


Fig1. VFB vs. PWM Duty

#### **PWM Control**

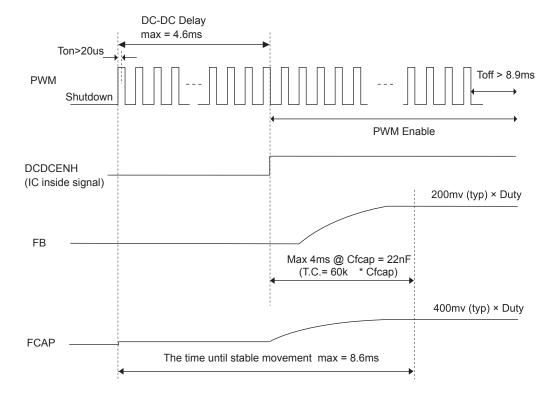


Fig2. Timing Diagram in PWM signal

#### **Open LED Protection**

If SW terminal voltage exceeds a threshold Vovp (41V typ) for 8 cycles, boost converter enters shutdown mode. In order to restart the IC, PWM setup signal is required again.

#### **Over Current Protection**

Current limit value for built-in power MOS is around 0.7A. The power MOS is turned off for each switching cycle when peak current through it exceeds the limit value.

#### **Under Voltage Lock Out (UVLO)**

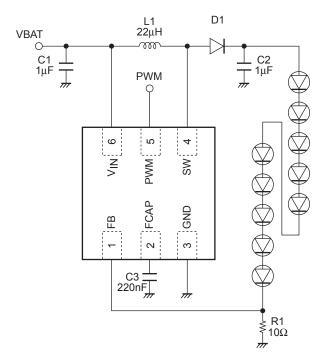
UVLO operation works when  $V_{\mbox{\footnotesize{IN}}}$  terminal voltage is below 2.2V.

#### **Thermal Shutdown**

When chip temperature is too high, boost converter is stopped.

#### **Application Circuit Diagram**

#### 10LEDs

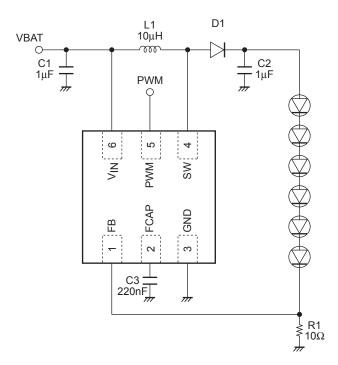


L1: VLS3012T-220M49 (TDK), VLF504015MT-220M (TDK)

D1: MBR0540T1 (ONsemi), NSR05F40 (ONsemi)

C2: GRM21BR71H105K (Murata), C1608X5R1H105K (TDK)

#### 6LEDs

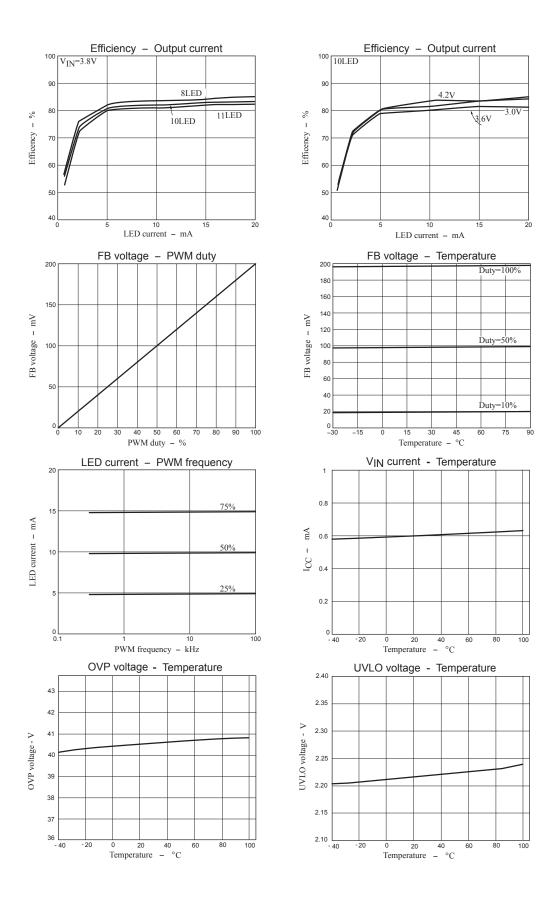


L1: VLS3012T-100M72 (TDK), VLF302512M-100M (TDK)

D1: MBR0540T1 (ONsemi), NSR05F40 (ONsemi)

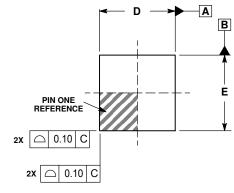
C2: GRM21BR71H105K (Murata), C1608X5R1H105K (TDK)

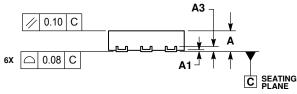
Typical Characteristics ( $V_{IN} = 3.6V$ ,  $L = 22\mu H$ , T = 25°C, unless otherwise specified)

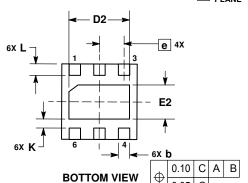


#### **PACKAGE DIMENSIONS**

UDFN6 2x2, 0.65P CASE 517AB







0.05 С

- NOTES:

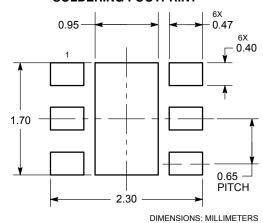
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

|     | MILLIMETERS |      |  |
|-----|-------------|------|--|
| DIM | MIN         | MAX  |  |
| Α   | 0.45        | 0.55 |  |
| A1  | 0.00 0.05   |      |  |
| A3  | 0.127 REF   |      |  |
| b   | 0.25 0.35   |      |  |
| D   | 2.00 BSC    |      |  |
| D2  | 1.50 1.70   |      |  |
| E   | 2.00 BSC    |      |  |
| E2  | 0.80        | 1.00 |  |
| е   | 0.65 BSC    |      |  |
| K   | 0.20        |      |  |
| L   | 0.25        | 0.35 |  |

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### LV52205MU is as follows.

#### **MARKING DIAGRAM**



= Device Code T5

= Date Code

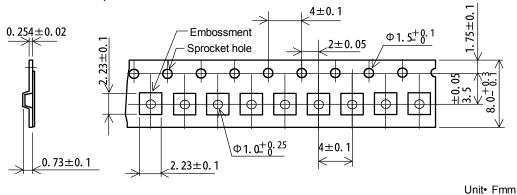
= Pb-Free Package

(Note: Microdot may be in either location)

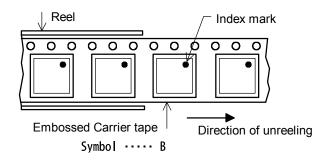
## Packing Specification of Embossed Carrier Taping UDFN6 (2.0×2.0) 3,000 pcs/reel

#### 1.EMBOSSED CARRIER TAPING

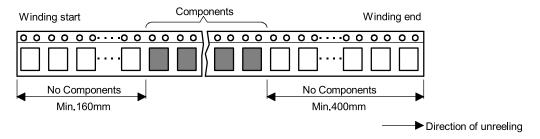
#### 1 - 1. Embossed carrier tape dimensions



#### 1 - 2 . Tape mounting direction



#### 1 - 3 .Reel winding start and reel winding end



#### 2.TAPE STRENGTH

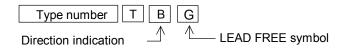
2 - 1 . Tensile strength of the carrier tape : Min. 10N

2 - 2 . Peel strength of the top cover tape

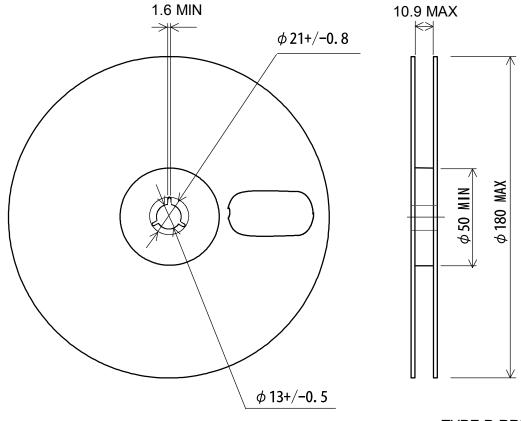
(a) Peel angle: 165° to 180° relative to the tape adhesive surface

(b)Peel rate: 300mm / minute (c)Peel of strength: 0.1N to 1.0N

#### 3 .PARTS No. ON BAR CODE LABEL



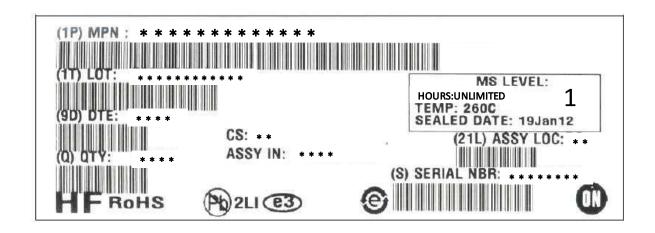
#### 4.REEL DIMENSIONS



TYPE:P-RRM-08B UNIT:mm

| Carrier tape type number | SANYO Package code | Maximum number of ICs contained (pcs.) |           | Packing form                                     |
|--------------------------|--------------------|--|-----------|--|
|                          |                    | Reel                                   | Inner box | Inner box. B50766P001                            |
| N22986D001               | UDFN6(2.0*2.0)     | 3,000                                  | 30,000    | 10 Reels contained Dimensions:mm 190 × 136 × 186 |

#### MPN Label



# Packing Method Inner box MPN Label Put 10 Reel into Inner box MPN Sticher

#### **ORDERING INFORMATION**

| Device       | Package                  | Shipping (Qty / Packing) |
|--------------|--------------------------|--------------------------|
| LV52205MUTBG | UDFN6 (2x2)<br>(Pb-Free) | 3000 / Tape & Reel       |

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